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Electrical ratings

Table 1. Absolute maximum ratings

Symbol	Parameter	Value	Unit
V_{DS}	Drain-source voltage	500	V
V_{GS}	Gate-source voltage	± 30	V
I_D	Drain current (continuous) at $T_C = 25^\circ\text{C}$	3	A
I_D	Drain current (continuous) at $T_C = 100^\circ\text{C}$	1.9	A
$I_{DM}^{(1)}$	Drain current (pulsed)	12	A
P_{TOT}	Total dissipation at $T_C = 25^\circ\text{C}$	45	W
$dv/dt^{(2)}$	Peak diode recovery voltage slope	4.5	V/ns
ESD	Gate-source human body model ($C = 100 \text{ pF}$, $R = 1.5 \text{ k}\Omega$)	2.8	kV
T_j	Operating junction temperature range	-55 to 150	$^\circ\text{C}$
T_{stg}	Storage temperature range		

1. Pulse width limited by safe operating area.

2. $I_{SD} \leq 3 \text{ A}$, $di/dt \leq 200 \text{ A}/\mu\text{s}$, $V_{DD} \leq V_{(BR)DSS}$.

Table 2. Thermal data

Symbol	Parameter	Value		Unit
		IPAK	DPAK	
$R_{thj-case}$	Thermal resistance junction-case	2.78		$^\circ\text{C}/\text{W}$
$R_{thj-amb}$	Thermal resistance junction-ambient	100		$^\circ\text{C}/\text{W}$
$R_{thj-pcb}^{(1)}$	Thermal resistance junction-pcb		50	$^\circ\text{C}/\text{W}$

1. When mounted on an 1-inch² FR-4, 2oz Cu board.

Table 3. Avalanche characteristics

Symbol	Parameter	Value	Unit
I_{AR}	Avalanche current, repetitive or not-repetitive (pulse width limited by T_j max)	3	A
E_{AS}	Single pulse avalanche energy (starting $T_j = 25^\circ\text{C}$, $I_D = I_{AR}$, $V_{DD} = 50 \text{ V}$)	120	mJ

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Electrical characteristics

($T_{CASE} = 25^\circ\text{C}$ unless otherwise specified)

Table 4. On/off states

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$, $I_D = 1\text{ mA}$	500			V
I_{DSS}	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$, $V_{DS} = 500\text{ V}$			1	μA
		$V_{GS} = 0\text{ V}$, $V_{DS} = 500\text{ V}$, $T_C = 125^\circ\text{C}$ ⁽¹⁾			50	μA
I_{GSS}	Gate-body leakage current	$V_{DS} = 0\text{ V}$, $V_{GS} = \pm 20\text{ V}$			± 10	μA
$V_{GS(\text{th})}$	Gate threshold voltage	$V_{DS} = V_{GS}$, $I_D = 50\text{ }\mu\text{A}$	3	3.75	4.5	V
$R_{DS(\text{on})}$	Static drain-source on resistance	$V_{GS} = 10\text{ V}$, $I_D = 1.5\text{ A}$		2.2	2.7	Ω

1. *Defined by design, not subject to production test.*

Table 5. Dynamic

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
C_{iss}	Input capacitance	$V_{DS} = 25\text{ V}$, $f = 1\text{ MHz}$, $V_{GS} = 0\text{ V}$	-	310		pF
C_{oss}	Output capacitance			49		
C_{rss}	Reverse transfer capacitance			10		
$C_{oss\text{ eq.}}^{(1)}$	Equivalent output capacitance	$V_{GS} = 0\text{ V}$, $V_{DS} = 0\text{ V}$ to 400 V	-	33		
Q_g	Total gate charge	$V_{DD} = 400\text{ V}$, $I_D = 3\text{ A}$, $V_{GS} = 0$ to 10 V (see Figure 14. Test circuit for gate charge behavior)	-	12		nC
Q_{gs}	Gate-source charge			3		
Q_{gd}	Gate-drain charge			7		

1. $C_{oss\text{ eq.}}$ is defined as a constant equivalent capacitance giving the same charging time as C_{oss} when V_{DS} increases from 0 to 80% V_{DSS} .

Table 6. Switching times

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 250\text{ V}$, $I_D = 1.5\text{ A}$, $R_G = 4.7\text{ }\Omega$, $V_{GS} = 10\text{ V}$ (see Figure 13. Test circuit for resistive load switching times and Figure 18. Switching time waveform)	-	10		ns
t_r	Rise time			7		
$t_{d(off)}$	Turn-off delay time			21		
t_f	Fall time			11		

Table 7. Source-drain diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
I_{SD}	Source-drain current		-		3	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		12	
$V_{SD}^{(2)}$	Forward on voltage	$I_{SD} = 3 \text{ A}, V_{GS} = 0 \text{ V}$	-		1.6	V
t_{rr}	Reverse recovery time	$I_{SD} = 3 \text{ A}, di/dt = 100 \text{ A}/\mu\text{s}$ $V_{DD} = 40 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$ (see Figure 15. Test circuit for inductive load switching and diode recovery times)	-	260		ns
Q_{rr}	Reverse recovery charge		-	935		nC
I_{RRM}	Reverse recovery current		-	7.2		A

1. Pulse width limited by safe operating area.
2. Pulsed: Pulse duration = 300 μs , duty cycle 1.5 %.

Table 8. Gate-source Zener diode

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)GSO}$	Gate-source breakdown voltage	$I_{GS} = \pm 1 \text{ mA}, I_D = 0 \text{ A}$	± 30	-	-	V

The built-in back-to-back Zener diodes are specifically designed to enhance the ESD performance of the device. The Zener voltage facilitates efficient and cost-effective device integrity protection, thus eliminating the need for additional external componentry.

2.1 Electrical characteristics (curves)

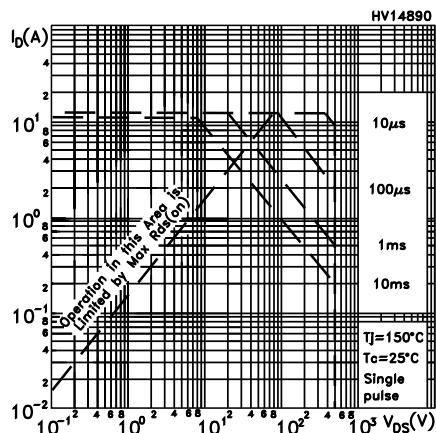
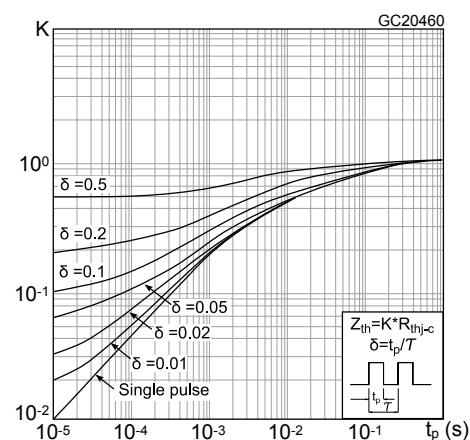
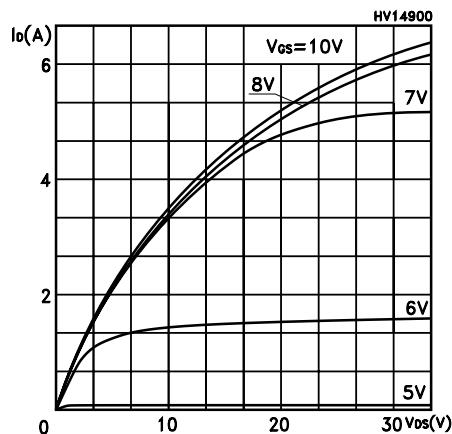
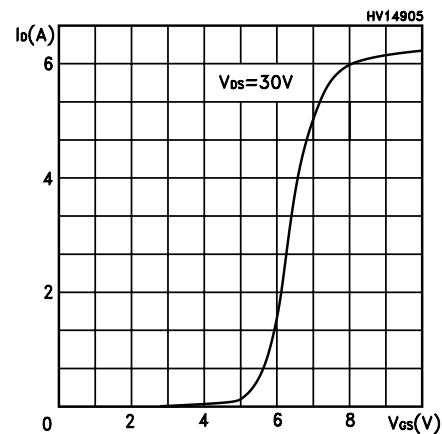
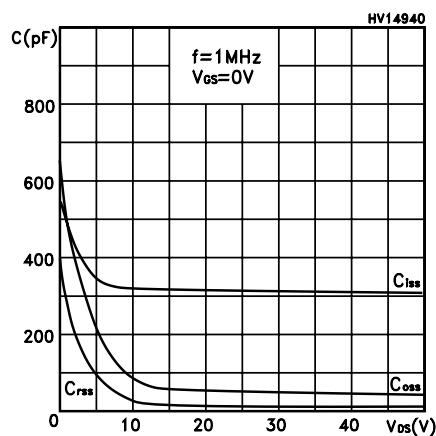
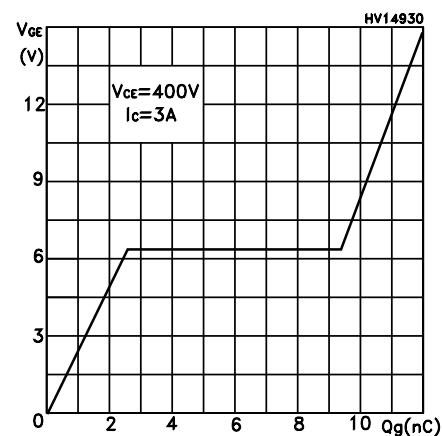
Figure 1. Safe operating area

Figure 2. Thermal impedance

Figure 3. Output characteristics

Figure 4. Transfer characteristics

Figure 5. Capacitance variations

Figure 6. Gate charge vs gate-source voltage


Figure 7. Normalized gate threshold voltage vs temperature

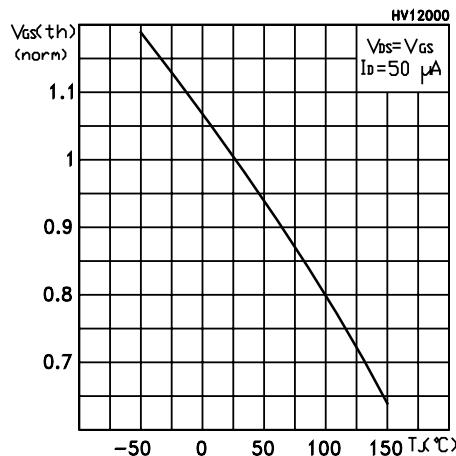


Figure 8. Static drain-source on resistance

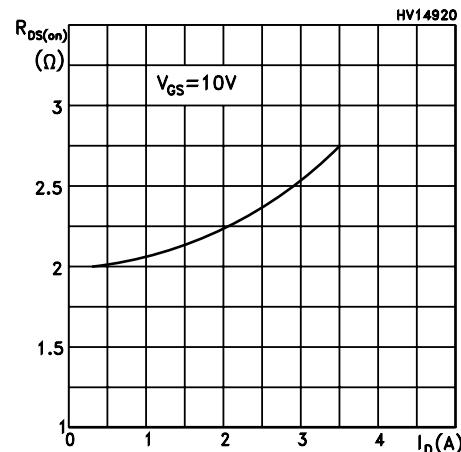


Figure 9. Source-drain diode forward characteristic

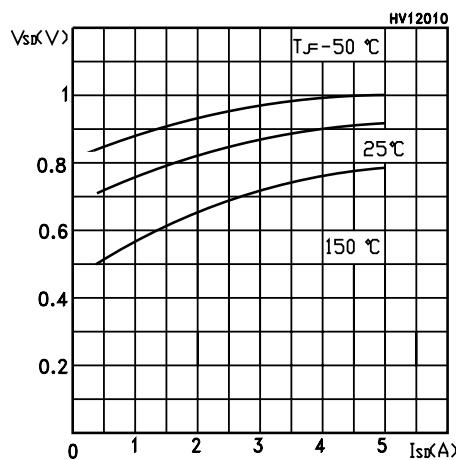


Figure 10. Maximum avalanche energy vs temperature

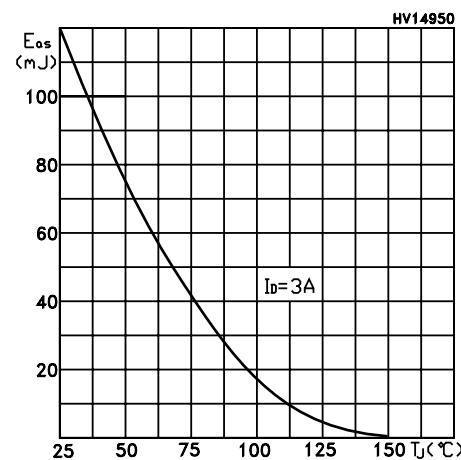


Figure 11. Normalized $V_{(BR)DSS}$ vs temperature

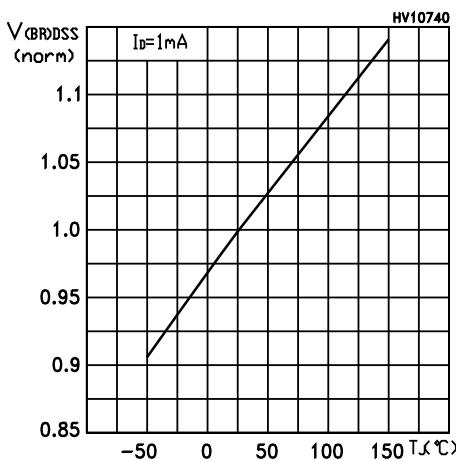
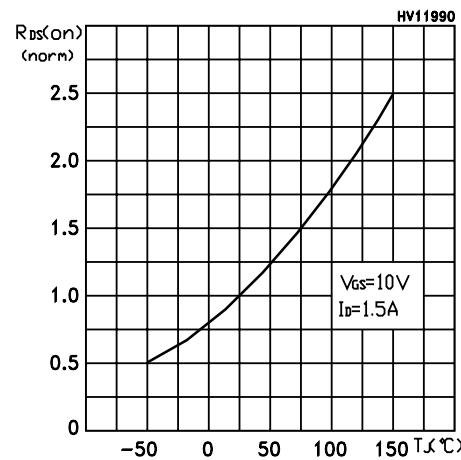


Figure 12. Normalized on resistance vs temperature



3 Test circuits

Figure 13. Test circuit for resistive load switching times

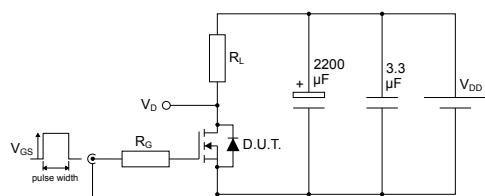


Figure 14. Test circuit for gate charge behavior

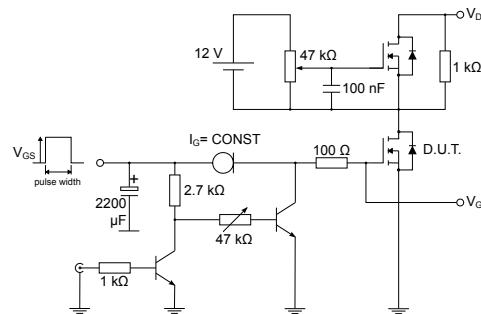


Figure 15. Test circuit for inductive load switching and diode recovery times

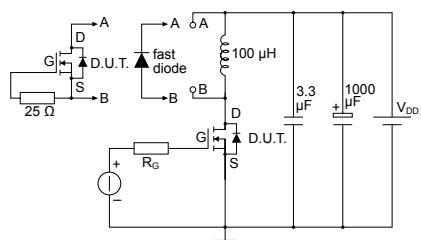


Figure 16. Unclamped inductive load test circuit

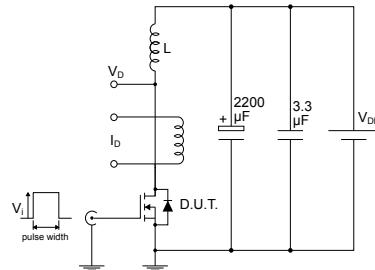


Figure 17. Unclamped inductive waveform

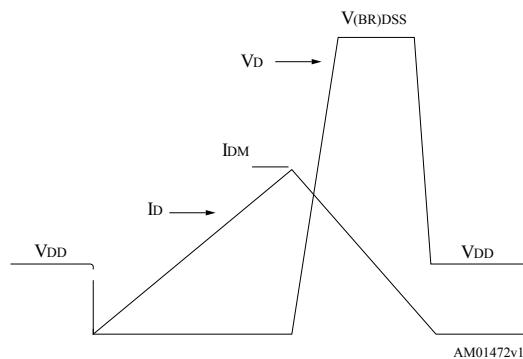
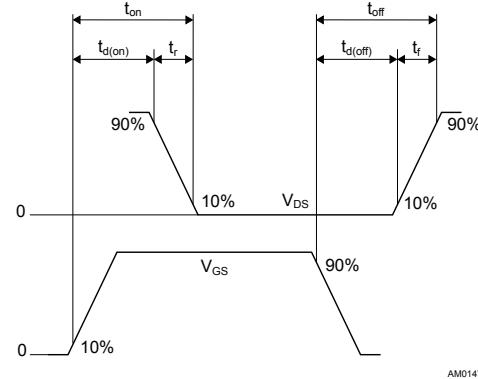


Figure 18. Switching time waveform

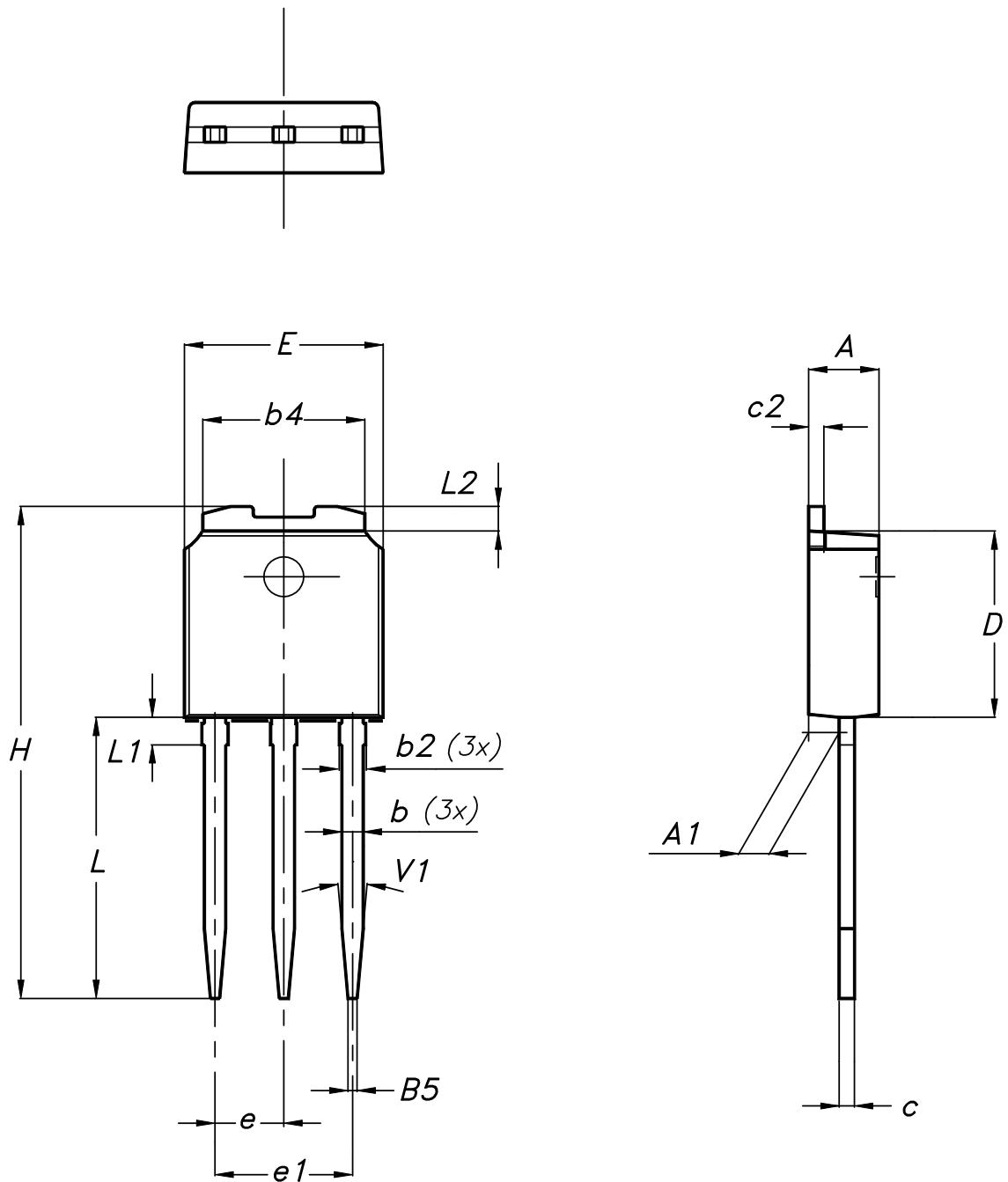


4**Package information**

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: www.st.com. ECOPACK® is an ST trademark.

4.1 IPAK (TO-251) type A package information

Figure 19. IPAK (TO-251) type A package outline



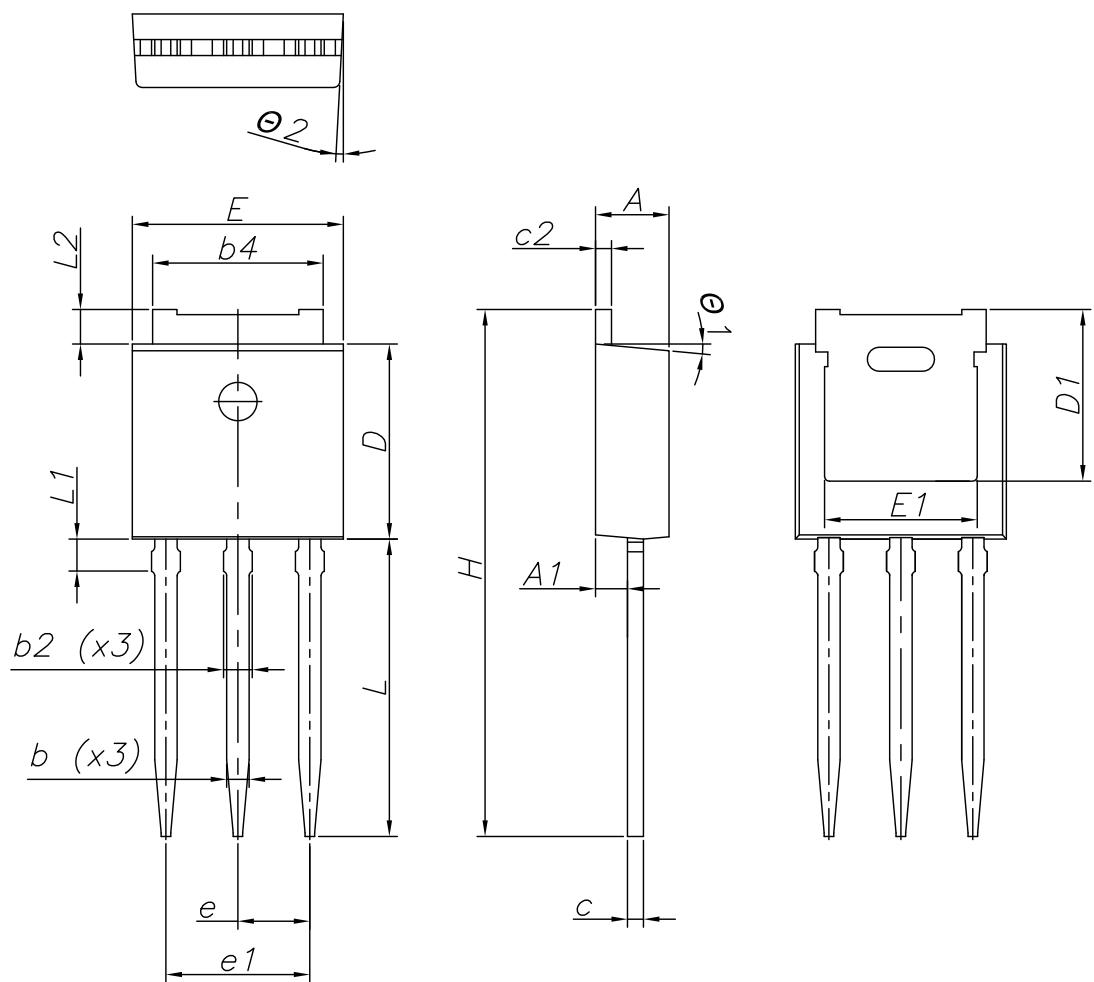
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Table 9. IPAK (TO-251) type A package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
b	0.64		0.90
b2			0.95
b4	5.20		5.40
B5		0.30	
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
E	6.40		6.60
e		2.28	
e1	4.40		4.60
H		16.10	
L	9.00		9.40
L1	0.80		1.20
L2		0.80	1.00
V1		10°	

4.2 IPAK (TO-251) type C package information

Figure 20. IPAK (TO-251) type C package outline



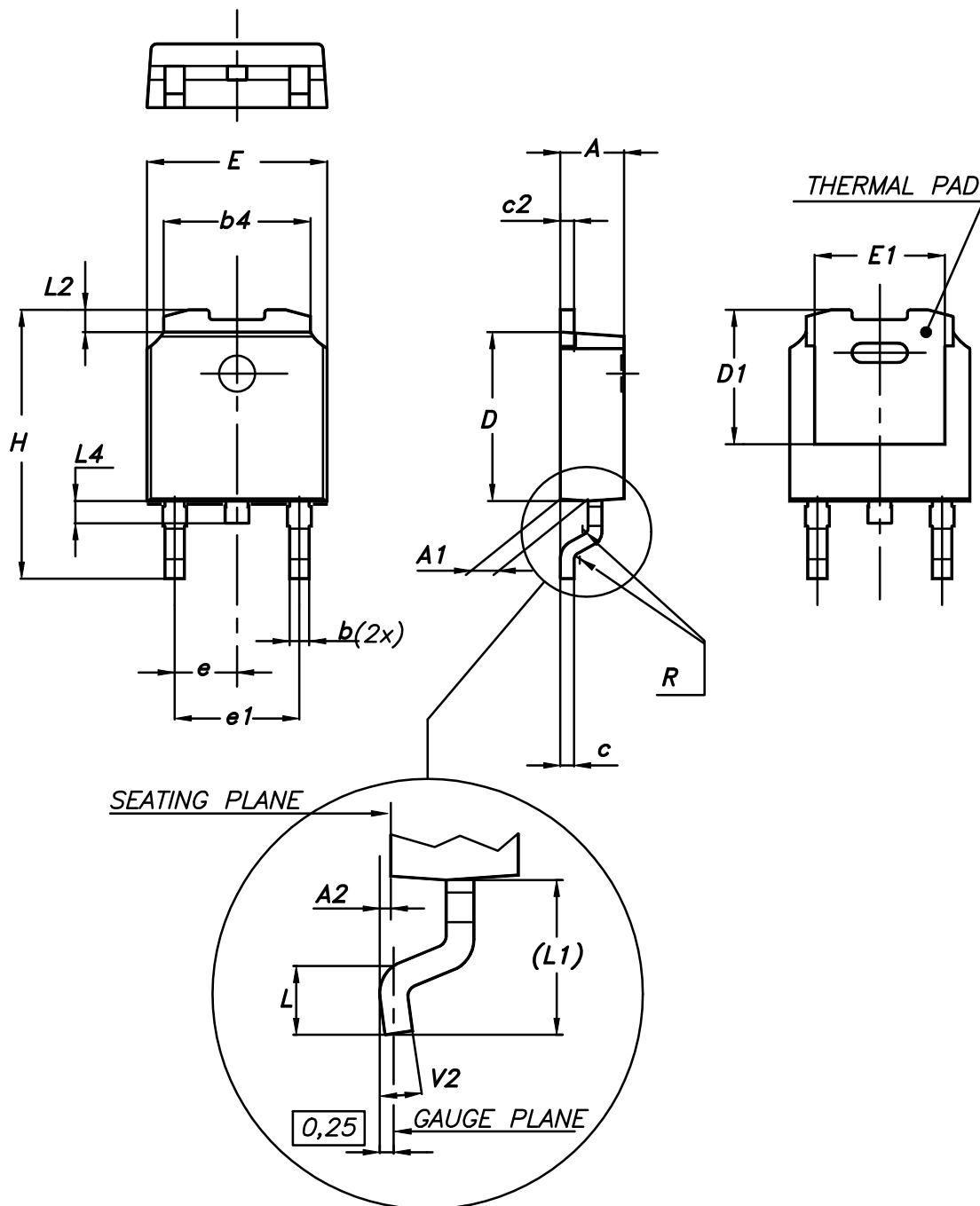
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Table 10. IPAK (TO-251) type C package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.35
A1	0.90	1.00	1.10
b	0.66		0.79
b2			0.90
b4	5.23	5.33	5.43
c	0.46		0.59
c2	0.46		0.59
D	6.00	6.10	6.20
D1	5.20	5.37	5.55
E	6.50	6.60	6.70
E1	4.60	4.78	4.95
e	2.20	2.25	2.30
e1	4.40	4.50	4.60
H	16.18	16.48	16.78
L	9.00	9.30	9.60
L1	0.80	1.00	1.20
L2	0.90	1.08	1.25
θ1	3°	5°	7°
θ2	1°	3°	5°

4.3 DPAK (TO-252) type A package information

Figure 21. DPAK (TO-252) type A package outline



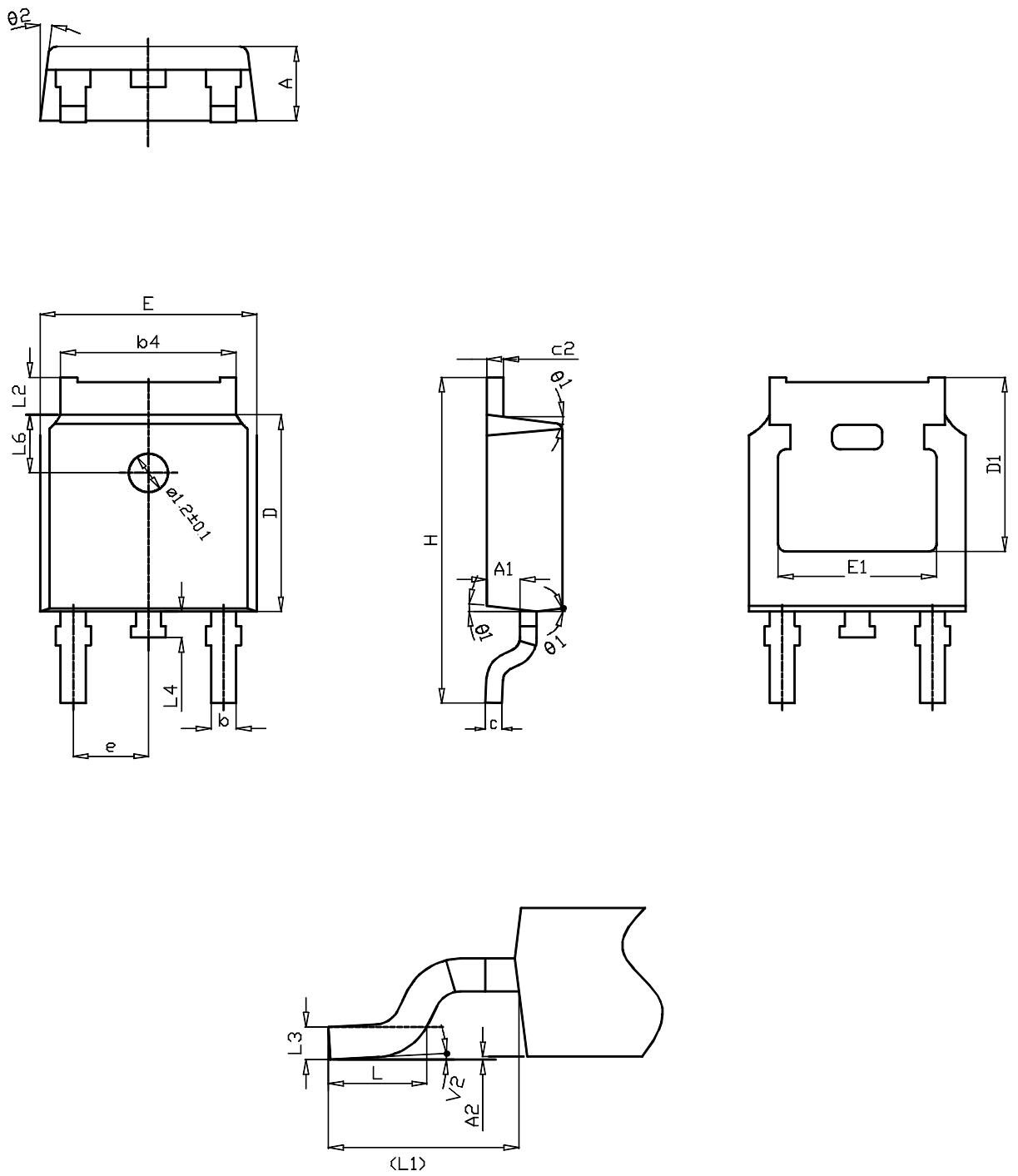
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Table 11. DPAK (TO-252) type A mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20		2.40
A1	0.90		1.10
A2	0.03		0.23
b	0.64		0.90
b4	5.20		5.40
c	0.45		0.60
c2	0.48		0.60
D	6.00		6.20
D1	4.95	5.10	5.25
E	6.40		6.60
E1	4.60	4.70	4.80
e	2.159	2.286	2.413
e1	4.445	4.572	4.699
H	9.35		10.10
L	1.00		1.50
(L1)	2.60	2.80	3.00
L2	0.65	0.80	0.95
L4	0.60		1.00
R		0.20	
V2	0°		8°

4.4 DPAK (TO-252) type C package information

Figure 22. DPAK (TO-252) type C package outline

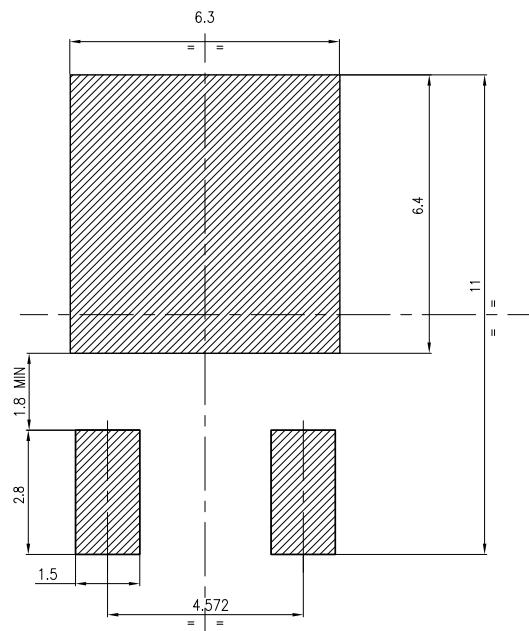


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Table 12. DPAK (TO-252) type C mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	2.20	2.30	2.38
A1	0.90	1.01	1.10
A2	0.00		0.10
b	0.72		0.85
b4	5.13	5.33	5.46
c	0.47		0.60
c2	0.47		0.60
D	6.00	6.10	6.20
D1	5.25		
E	6.50	6.60	6.70
E1	4.70		
e	2.186	2.286	2.386
H	9.80	10.10	10.40
L	1.40	1.50	1.70
L1	2.90 REF		
L2	0.90		1.25
L3	0.51 BSC		
L4	0.60	0.80	1.00
L6	1.80 BSC		
θ1	5°	7°	9°
θ2	5°	7°	9°
V2	0°		8°

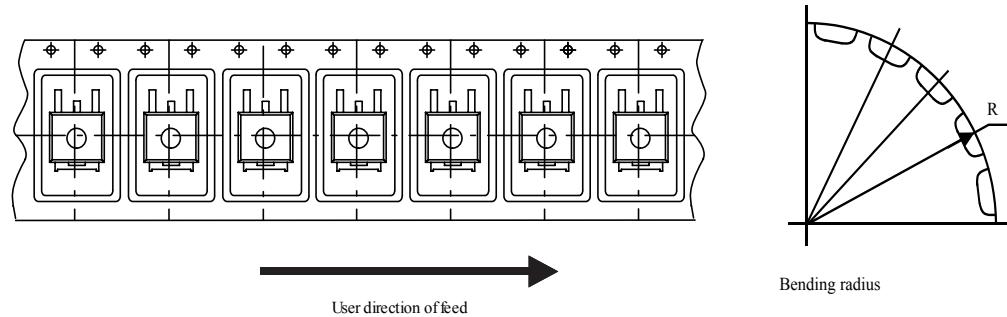
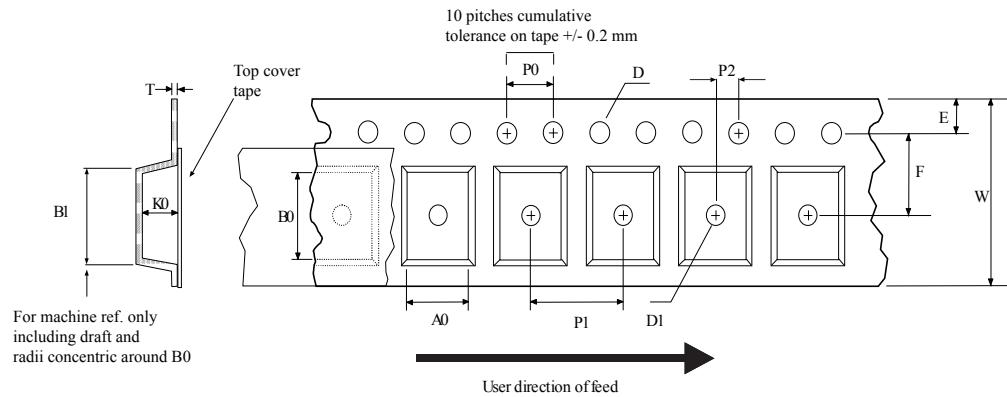
Figure 23. DPAK (TO-252) recommended footprint (dimensions are in mm)



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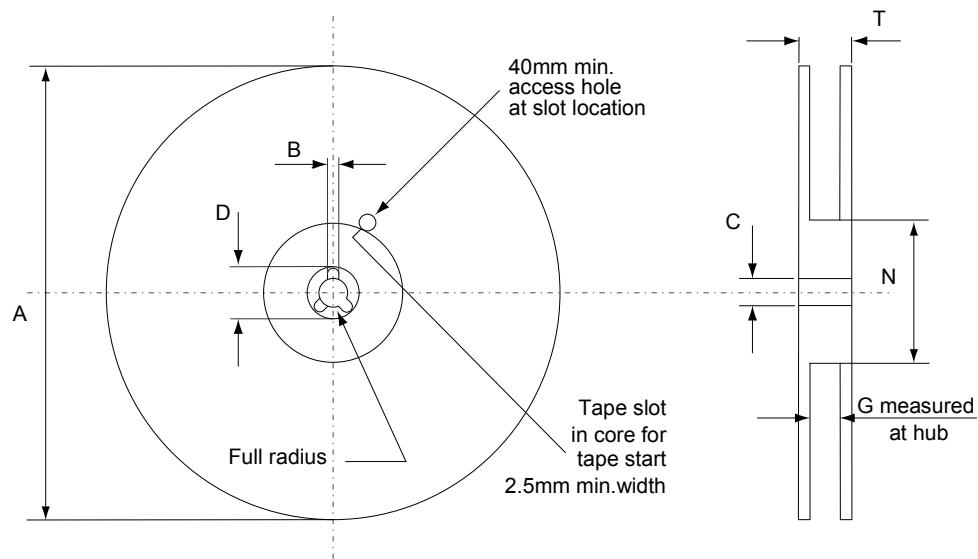
4.5 DPAK (TO-252) packing information

Figure 24. DPAK (TO-252) tape outline



AM08852v1

Figure 25. DPAK (TO-252) reel outline



AM06038v1

Table 13. DPAK (TO-252) tape and reel mechanical data

Tape			Reel		
Dim.	mm		Dim.	mm	
	Min.	Max.		Min.	Max.
A0	6.8	7	A		330
B0	10.4	10.6	B	1.5	
B1		12.1	C	12.8	13.2
D	1.5	1.6	D	20.2	
D1	1.5		G	16.4	18.4
E	1.65	1.85	N	50	
F	7.4	7.6	T		22.4
K0	2.55	2.75			
P0	3.9	4.1	Base qty.		2500
P1	7.9	8.1	Bulk qty.		2500
P2	1.9	2.1			
R	40				
T	0.25	0.35			
W	15.7	16.3			

5 Ordering information

Table 14. Order codes

Order code	Marking	Package	Packing
STD4NK50Z-1	D4NK50Z	IPAK	Tube
STD4NK50ZT4		DPAK	Tape and reel

Revision history

Table 15. Document revision history

Date	Version	Changes
09-Dec-2002	2	Updated document.
20-Aug-2018	3	Removed maturity status indication from cover page. The document status is production data. The part numbers STP4NK50Z and STP4NK50FP have been moved to a separate datasheet. Updated Section 1 Electrical ratings , Section 2 Electrical characteristics and Section 4 Package information . Added Section 5 Ordering information . Minor text changes.

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